



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

**Nishant Sinha**

**Serial No.: 10/668,914**

**Filed: September 23, 2003**

**For: PROCESS AND INTEGRATION  
SCHEME FOR FABRICATING  
CONDUCTIVE COMPONENTS,  
THROUGH-VIAS AND  
SEMICONDUCTOR COMPONENTS  
INCLUDING CONDUCTIVE THROUGH-  
WAFER VIAS**

**Confirmation No.: 2525**

**Examiner: Ha T. Nguyen**

**Group Art Unit: 2812**

**Attorney Docket No.: 2269-5859US**

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

September 9, 2004  
Date

Signature

Joseph A. Walkowski  
Name (Type/Print)

**SUPPLEMENTAL PRELIMINARY AMENDMENT**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please revise the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 14 of this paper.

09/15/2004 JADD01 00000008 10668914

01 FC:1201 430.00 OP  
02 FC:1202 432.00 OP